



PATENT

YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

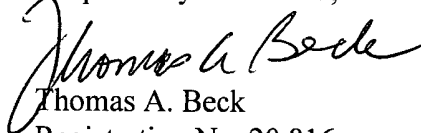
In re Application of : D.Y.Shih, et al.
Serial Number : 09/254,769
Filing Date : March 11, 1999
Examiner : V. Nguyen
Group Art Unit : 2858
For : WAFER SCALE HIGH DENSITY
PROBE ASSEMBLY,
APPARATUS FOR USE THEREOF
AND METHODS OF
FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Washington, D.C. 20231

Sir:

Applicants respectfully file this response to the Official Action dated December 7, 2000 wherein the Examiner requested submission of an Abstract of the Disclosure. A response to the substantive issues raised in the Official Action is being filed concurrently.

Respectfully Submitted,



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I hereby certify that this paper is being transmitted by First Class mail addressed to Commissioner of Patents & Trademarks, Washington, D.C. 20231

Signature: 
Name: Thomas A. Beck

Date: April 07, 2001

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